

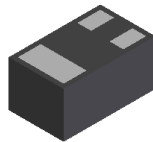
**Features**

- Fast Switching Speed
- Ultra-Small Leadless Surface Mount Package (1.0 \* 0.6mm)
- Ultra-Low Profile Package (0.5mm)
- Low Forward Voltage
- Fast Reverse Recovery
- Low Capacitance
- **Totally Lead- Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

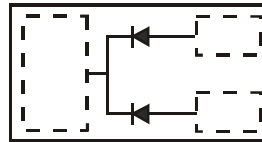
**Mechanical Data**

- Case: X1-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Bar
- Terminals: Finish – NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 <sup>(e4)</sup>
- Weight: 0.0009 grams (Approximate)

X1-DFN1006-3



Bottom View



Top View  
Internal Schematic

**Ordering Information** (Note 4)

Part Number	Case	Packaging
BAV70LP-7	X1-DFN1006-3	3,000/Tape & Reel

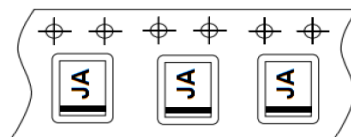
- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

**Marking Information**



Top View  
Bar Denotes Cathode Side

JA = Product Type Marking Code



**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V <sub>RM</sub>	100	V
Peak Repetitive Reverse Voltage	V <sub>R(RM)</sub>	75	V
Working Peak Reverse Voltage	V <sub>R(WM)</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	53	V
Forward Continuous Current (Note 5)	I <sub>FM</sub>	300	mA
Average Rectified Output Current (Note 5)	I <sub>O</sub>	150	mA
Repetitive Peak Forward Current	I <sub>FRM</sub>	450	mA
Non-Repetitive Peak Forward Surge Current	I <sub>FSM</sub>	@ t = 1.0μs	2.0
		@ t = 1.0s	1.0

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	400	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R <sub>θJA</sub>	312	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V <sub>(BR)R</sub>	75	—	V	I <sub>R</sub> = 2.5μA
Forward Voltage	V <sub>F</sub>	—	0.715	V	I <sub>F</sub> = 1.0mA
			0.855		I <sub>F</sub> = 10mA
			1.0		I <sub>F</sub> = 50mA
			1.25		I <sub>F</sub> = 150mA
Reverse Current (Note 6)	I <sub>R</sub>	—	2.5	μA	V <sub>R</sub> = 75V
			50		V <sub>R</sub> = 75V, T <sub>J</sub> = +150°C
			30		V <sub>R</sub> = 25V, T <sub>J</sub> = +150°C
			25		V <sub>R</sub> = 20V
Total Capacitance	C <sub>T</sub>	—	2.0	pF	V <sub>R</sub> = 0, f = 1.0MHz
Reverse Recovery Time	t <sub>RR</sub>	—	4.0	ns	I <sub>F</sub> = I <sub>R</sub> = 10mA, I <sub>RR</sub> = 0.1 x I <sub>R</sub> , R <sub>L</sub> = 100Ω

Notes: 5. Part mounted on FR-4 board with recommended pad layout, please see <http://www.diodes.com/package-outlines.html> for the latest version.  
6. Short duration pulse test used to minimize self-heating effect.

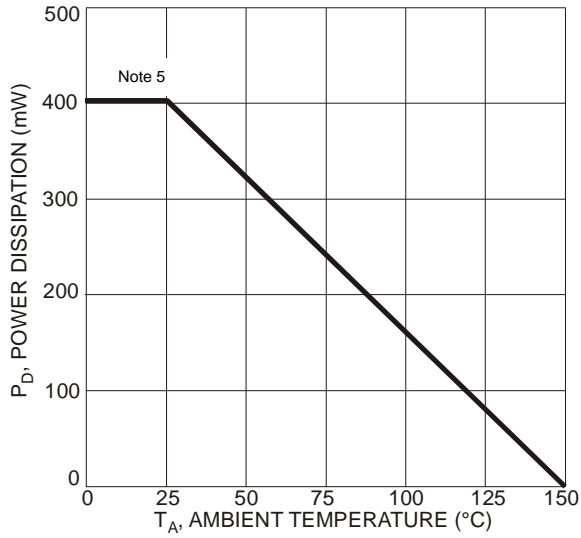


Fig. 1 Power Derating Curve

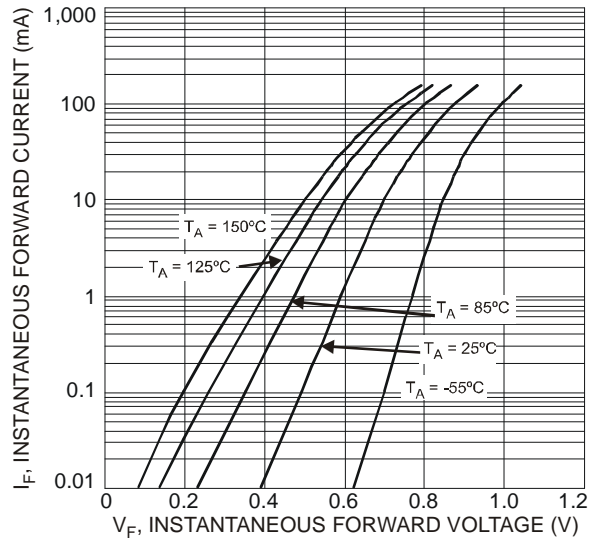


Fig. 2 Typical Forward Characteristics, Per Element

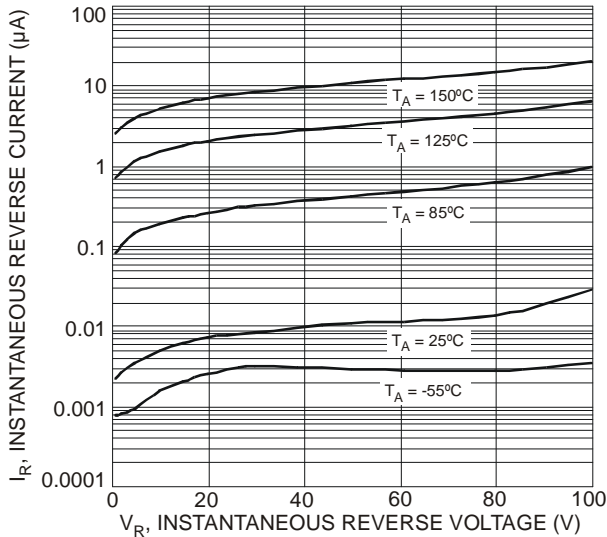


Fig. 3 Typical Reverse Characteristics, Per Element

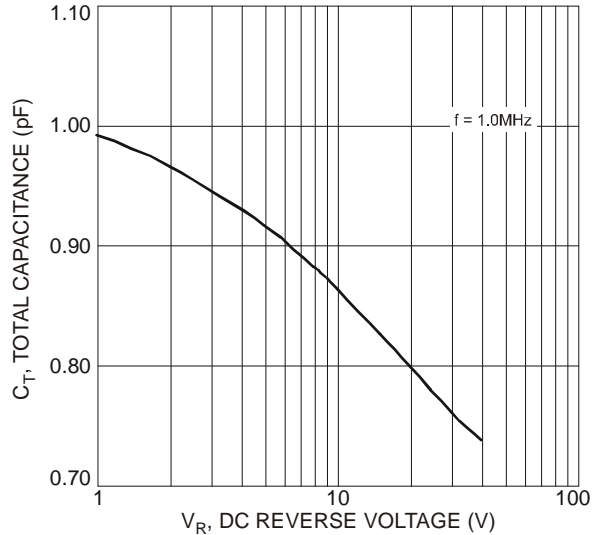
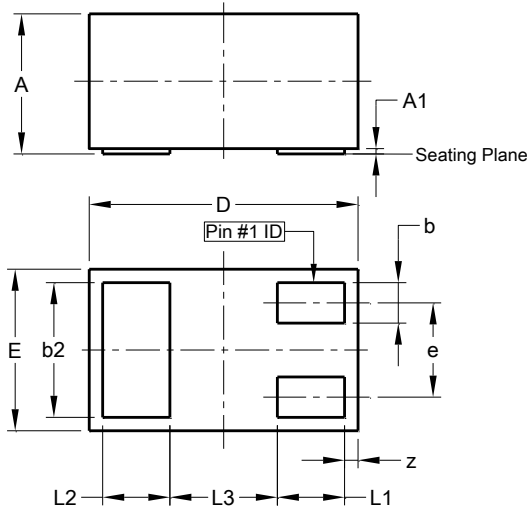


Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X1-DFN1006-3**

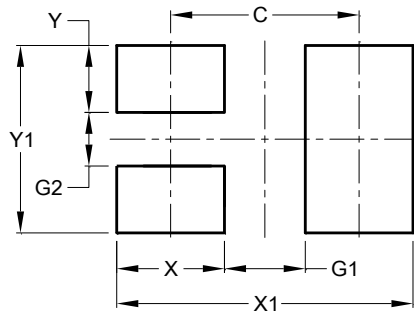


X1-DFN1006-3			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0.00	0.05	0.03
b	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	-	-	0.40
z	0.02	0.08	0.05
<b>All Dimensions in mm</b>			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X1-DFN1006-3**



Dimensions	Value (in mm)
C	0.70
G1	0.30
G2	0.20
X	0.40
X1	1.10
Y	0.25
Y1	0.70

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